

# **Product Compliance Declaration**

Please see <u>www.molex.com</u> for the most up-to-date information.

Contact Inf	ormation		
	ormation		
Name	Molex Product Compliance	E-Mail	Product.Compliance@molex.com
Part Inform	ation		
Part Number	0532610271	Part Weight	0.118808G
Part Name	1.25 WtB Wafer Assy 2Ckt EmbsTp Pkg		

#### **Product Composition**

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
1.25 WtB Wafer Assy 2Ckt EmbsTp Pkg	Assembly		100	0.118808
1.25 W-B SMT SOLDER PIN	Component		17.5209	0.020816
Tin Plating	Material		0.1752	0.000208
Tin	Substance	7440-31-5	0.1752	0.000208
1.25 W-B SMT SOLDER PIN	Component		17.1705	0.0204
Phosphor Bronze 5% Unplated	Material		17.1705	0.0204
Copper	Substance	7440-50-8	16.2862	0.019349
Tin	Substance	7440-31-5	0.8585	0.00102
Phosphorus	Substance	7723-14-0	0.0258	0.000031
Nickel Plating	Material		0.1752	0.000208
Nickel	Substance	7440-02-0	0.1752	0.000208
Fitting Nail Chain W/Plt	Assembly		24.9073	0.029592
FITTING NAIL FOR 53261	Component		24.4091	0.029

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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Phosphor Bronze 5% Unplated	Material		24.4091	0.029
Copper	Substance	7440-50-8	23.152	0.027507
Tin	Substance	7440-31-5	1.2205	0.00145
Phosphorus	Substance	7723-14-0	0.0366	0.000044
Tin Plating	Material		0.2491	0.000296
Tin	Substance	7440-31-5	0.2491	0.000296
Nickel Plating	Material		0.2491	0.000296
Nickel	Substance	7440-02-0	0.2491	0.000296
1.25 W-B WAFER FORSMT R/A	Component		57.5717	0.0684
PA46 GF30 NATURAL	Material		57.5717	0.0684
PA46	Substance		23.2878	0.027668
GF-Fibre	Substance		17.5594	0.020862
Flame Retardant, ISO 1043-4 FR(17)	Substance		12.6658	0.015048
Antimonytrioxide	Substance	1309-64-4	3.4543	0.004104
Further Additives, not to declare	Substance	system	0.6045	0.000718

#### **ROHS** Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

#### **Contained Substances Exceeding Threshold**

None

#### Exemptions

None

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# **REACH-SVHC** Declaration Information

Regulatory Revision D(2022)4187-DC (10 June 2022)

#### **Contained Substances Exceeding Threshold**

None

### **GADSL Declaration Information**

Regulatory Revision GADSL imported from IMDS

#### **Contained Substances Exceeding Threshold**

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	500	Yes
Lead	Phosphor Bronze 5% A (CA510)	*Note	250	Yes
Lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	500	Yes
Antimonytrioxide	PA46 GF30 NATURAL	*Note	60,000	Yes
nickel	Ep-Ni	*Note	997,500	Yes
Copper	Phosphor Bronze 5% A (CA510)	*Note	943,350	Yes

\*Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

#### Exemptions

Part Name	Exemption
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits
Phosphor Bronze 5% A (CA510)	44 Concentration within acceptable GADSL limits
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/ cm2/week)

# **HFLH Declaration Information**

Regulatory Revision IEC 61249-2-21

#### **Contained Substances Exceeding Threshold**

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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Bromine and its compounds	PA46 GF30 NATURAL	900	220,000	Yes
Bromine and Chlorine combined	PA46 GF30 NATURAL	1,500	220,000	Yes

# **China ROHS Declaration Information**

Part Number 0532610271 Part Name 1.25 WtB Wafer A Pkg	Assy 2Ckt EmbsTp							
Part Information				Haz	zardous S	Substance	s	
Components			Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
1.25 WtB Wafer Assy 2Ckt Emb	sTp Pkg		0	0	0	0	0	0
1.25 W-B SMT SOLDER PIN			0	0	0	0	0	0
1.25 W-B SMT SOLDER PIN			0	0	0	0	0	0
Fitting Nail Chain W/Plt		0	0	0	0	0	0	
FITTING NAIL FOR 53261		0	0	0	0	0	0	
1.25 W-B WAFER FORSMT R/A		0	0	0	0	0	0	

# **Additional Information**

Annex XVII to REACH (76/769/EEC)	Compliant
Regulation (EU) 2019/1021 (POP)	Compliant

# **Process Information**

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A
Solder Alloy	N/A
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A

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Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

Jul 28, 2022

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